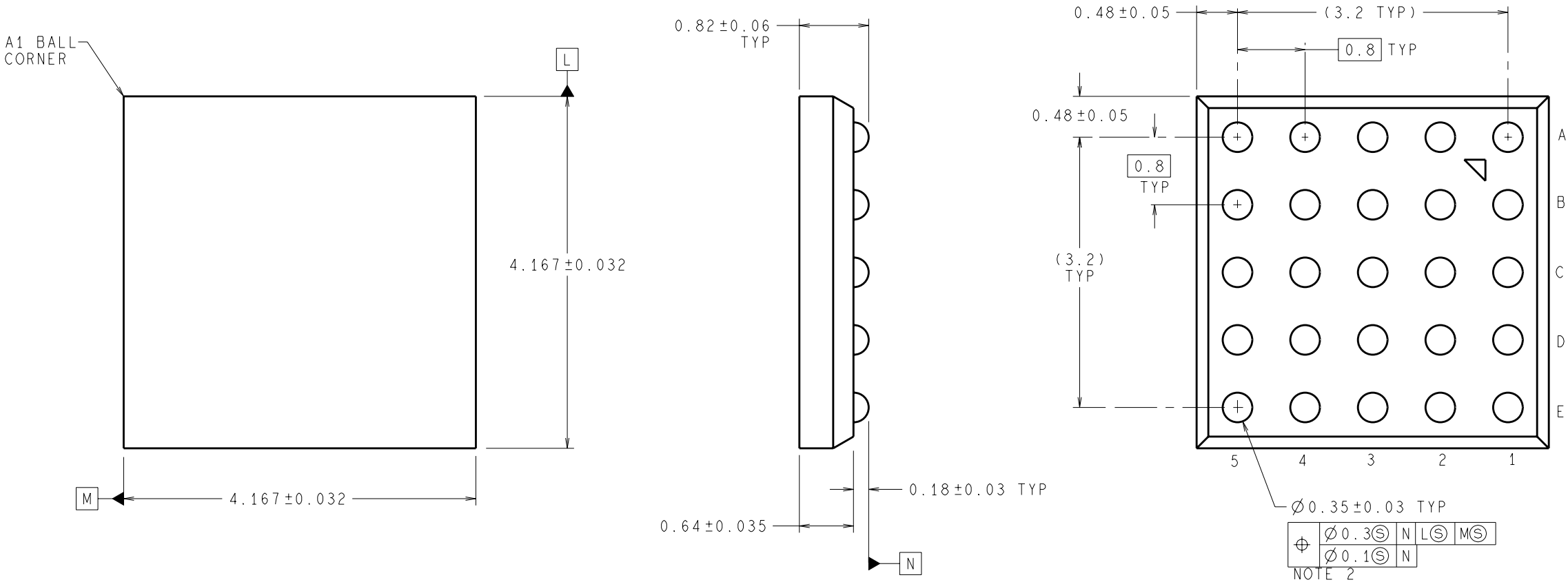


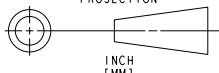
REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	460	11/28/2001	TL/AP



DIMENSIONS ARE IN MILLIMETERS

NOTES: UNLESS OTHERWISE SPECIFIED

- SOLDER BALL COMPOSITION: 62% Sn, 36% Pb, 2% Ag.
- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM N.
- NO JEDEC REGISTRATION AS OF NOVEMBER 2001.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090 BGA, SHELL-OP, 4.167 X 4.167 X 0.82mm, 25 BALL, 0.8mm PITCH			
DRAWN	T. LEQUANG	11/28/2001					
DFTG. CHK.	MARTA SUCHY	11/28/2001					
ENGR. CHK.	ASHOK PRABHU	11/28/2001					
 PROJECTION INCH [MM]				SCALE	SIZE	DRAWING NUMBER	REV
				N/A	C	(SC)MKT-SGA25A	A
				DO NOT SCALE DRAWING		SHEET 1 of 1	